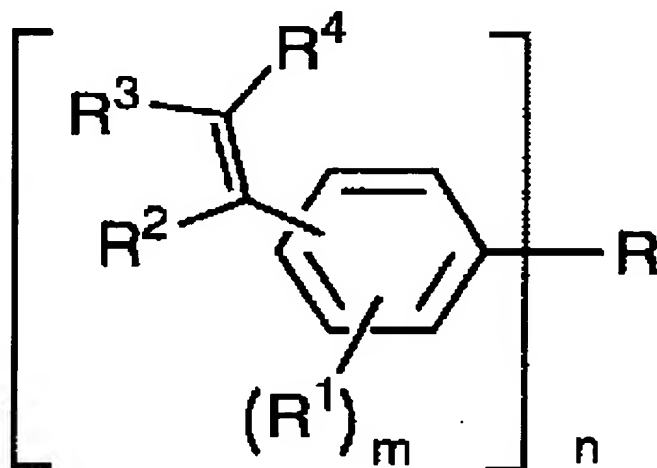


ABSTRACT OF THE DISCLOSURE

There is provided a resin composition suitable for insulating materials for use in electronic parts for handling high frequency signals, low in dielectric constant and low in dielectric dissipation factor, capable of forming thin film by low temperature curing, excellent in the adhesiveness to conductive foil and excellent in flexibility; a cured product derived from the composition; and a film substrate and an electronic part using the composition.

A resin composition, low in dielectric dissipation factor, comprising: a crosslinking component having a weight averaged molecular weight of 1,000 or less and a plurality of styrene groups represented by the following general formula:



wherein R represents a hydrocarbon moiety; each R¹, which may be the same or different, represents a hydrogen atom or a C₁₋₂₀ hydrocarbon group; R², R³ and R⁴, which may be the same or different, represent a hydrogen atom or a C₁₋₆ alkyl group; and m is an integer of 1 to 4, and n is an integer of 2 or more; and

a rubber component having a weight averaged molecular weight of 5,000 or more and styrene units; a cured product; and a film substrate and an electronic part using the composition.